



Material Content Data Sheet



Sales Product Name		IPG16N10S4-61		Issued		22. January 2018		
MA#		MA001616830						
Package		PG-TDSON-8-4		Weight*		95.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.384	1.44	1.44	14418	14418
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		140	
	non noble metal	iron	7439-89-6	0.045	0.05		466	
	non noble metal	copper	7440-50-8	44.654	46.53	46.59	465228	465834
	non noble metal	aluminium	7429-90-5	0.717	0.75	0.75	7472	7472
wire	non noble metal	aluminium	7429-90-5	0.717	0.75	0.75	7472	7472
encapsulation	organic material	carbon black	1333-86-4	0.092	0.10		956	
	plastics	epoxy resin	-	6.512	6.78		67846	
	inorganic material	silicondioxide	60676-86-0	39.256	40.90	47.78	408990	477792
leadfinish	non noble metal	tin	7440-31-5	1.308	1.36	1.36	13624	13624
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	500	501
solder	non noble metal	tin	7440-31-5	0.039	0.04		407	
	noble metal	silver	7440-22-4	0.049	0.05		509	
	non noble metal	lead	7439-92-1	1.866	1.94	2.03	19443	20359
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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